

Exhibit 23



Hybrid Memory Cube C O N S O R T I U M

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HMCC has delivered the first Draft HMC Specification to Adopters! Be among the first to review by visiting the [About Us](#) page and requesting the Adopters Agreement.

We have officially announced the date and time of our next HMCC Webinar! The purpose of this webinar will be to review the recent updates to HMCC Rev 2.1. Please visit our [events page](#) to register and learn more. Dial-in information for the webinar will follow soon.

- [Discover The Technology](#)
- [Review the FAQ](#)
- [Learn How To Participate](#)

About the Consortium

The goal of the Hybrid Memory Cube Consortium is to facilitate HMC Integration into a wide variety of systems, platforms and applications by defining an adoptable industry-wide interface that enables developers, manufacturers and enablers to leverage this revolutionary technology.

How to Get Involved

The HMCC is open to an unlimited number of adopters who can apply for access to the HMC Specification and participate in the specification review, discussion and development.

- To receive an executable Adopter Agreement fill out and submit an [Application](#).

Have questions about the HMCC or becoming an Adopter? [Contact Us](#)

HMC Consortium Participants

Founded by Micron Technology and Samsung Electronics Co. Ltd., the Hybrid Memory Cube Consortium is managed by a group of eight developers, each of whom has equal voice and voting power on the final specification. This group is responsible for managing the organization, attending management and adoption meetings, and developing and optimizing the ongoing HMC interface specification.

Developer Members:



[Altera Corporation](#)



[ARM](#)



[IBM](#)



[Micron Technology, Inc](#)



[Open-Silicon, Inc.](#)



[Samsung Electronics Co., Ltd](#)



[Semtech*](#)



[SK hynix](#)



[Xilinx, Inc.](#)

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Adopter Members:

- [Accel, Ltd.](#)
- [Achronix Semiconductor Corporation](#)
- [Adaptive Array Systems Limited](#)
- [ADATA Technology Co., Ltd.](#)
- [AIRBUS](#)
- [Alchip Technologies Ltd.](#)
- [Altior](#)
- [Analog Bits](#)
- [APIC Corporation](#)
- [Ariba Design](#)
- [Arnold & Richter Cine Technik](#)
- [Asic Research Inc.](#)
- [Industrial Technology Research Institute \(ITRI\)](#)
- [Infinera Corporation](#)
- [Information Sciences Institute / University of Southern California](#)
- [Inphi Corporation](#)
- [Institute of Computing Technology, Chinese Academy of Sciences](#)
- [Istituto Nazionale di Fisica Nucleare](#)
- [Integrated Device Technology](#)
- [Intellitech Corporation](#)
- [Pico Computing](#)
- [Praesum Communications](#)
- [Ram Charan Company Private Limited](#)
- [Renesas Electronics Corporation](#)
- [ROHDE & SCHWARZ GmbH & Co. KG](#)
- [S3Craft Technologies](#)
- [Science & Technology Innovation](#)
- [SEAKR Engineering](#)
- [Semtech Corporation - Snowbust IP](#)
- [Signal Integrity Software, Inc. \(SiSoft\)](#)
- [SIMMTECH Co., Ltd.](#)
- [Sintecs BV](#)
- [SICA South Africa](#)

- Bayside Design Inc.
- BroadPak Corporation
- Brocade Communications Systems, Inc.
- Cadence Design Systems, Inc.
- Calnex Solutions Ltd.
- Cascade Microtech
- Compass-EOS
- Convey Computer Corporation
- Cray Inc.
- DAVE Srl
- Design Magnitude Inc.
- Dream Chip Technologies GmbH
- Engineering Physics Center of MSU
- Esencia Technologies Inc.
- eSilicon Corporation
- Exablade Corporation
- EZchip Semiconductor Ltd.
- FirstPass Engineering
- FormFactor, Inc.
- Fujitsu Advanced Technologies Ltd.
- Galaxy Computer System Co., Ltd.
- GDA Technologies
- GiDEL
- GLOBALFOUNDRIES
- Google Inc.
- GraphStream Incorporated
- Green Wave Systems Inc.
- HGST, a Western Digital Company
- HiSilicon Technologies Co., Ltd.
- HiTech Global
- HOY Technologies
- Huawei Technologies
- Ircona
- ISI / Nallatech
- Israel Institute of Technology
- Ixia
- Juniper Networks
- KALRAY
- Korea Advanced Institute of Science and Technology
- Lawrence Livermore National Laboratory
- LeCroy Corporation
- Liquid Logic, LLC
- LogicLink Design, Inc.
- Lomonosov Moscow State University
- Luxtera, Inc.
- Marvell
- Mattozetta Technologies
- Maxeler Technologies Ltd.
- MediaTek
- Mentor Graphics
- Miranda Technologies Partnership
- Mobiveil, Inc.
- Module-Projects
- Montage Technology, Inc.
- Napatech A/S
- National Instruments
- NEC Corporation
- Netronome
- New Global Technology
- Northwest Logic
- Obsidian Research
- OmniPhy
- Oregon Synthesis
- Palo Alto Networks
- Pennsylvania State University
- Pentek, Inc.
- Percraft
- Inc.
- STMicroelectronics
- Suitcase TV Ltd.
- Sundance DSP, Inc.
- Suzhou Powercore Technology Co. Ltd.
- Synopsys Inc.
- Synthetic Intelligence
- T-Platforms
- Tabula
- Tech-Trek Ltd.
- Technion - Israel Institute of Technology
- Technische Universität Dresden, HPSN
- Technolution B.V.
- TekStart LLC
- Tektronix, Inc.
- Teledyne LeCroy
- Teradyne, Inc.
- Telesoft Technologies Ltd
- The Regents of the University of California
- Tiler Corporation
- Tipalo GmbH
- Tongji University
- TU Kaiserslautern, Lehrstuhl Entwurf Mikroelektronischer Systeme
- UC Irvine
- United Microelectronics Corporation
- Università di Bologna - DEI
- University of Heidelberg ZITI (Center for Computer Engineering)
- University of Rochester
- University of Southern California
- Wave Semiconductor
- Winbond Electronics Corporation
- Woodward McCoach, Inc.
- Wuhan Integrated Circuit Center
- ZTE Corporation